

## Description

The IRFR3410TRPBF uses advanced trench technology

to provide excellent  $R_{\text{DS}(\text{ON})},$  low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

### **General Features**

 $V_{DS} = 100V I_D = 30A$ 

 $R_{DS(ON)} < 48m\Omega @ V_{GS}=10V$ 

# Application

Battery protection

Load switch

Uninterruptible power supply

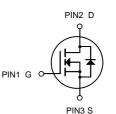
### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
IRFR3410TRPBF	TO-252-2L	FR3410 XXXX	2500

#### Absolute Maximum Ratings Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	100	V
Vgs	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>		
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>		
Ідм	Pulsed Drain Current <sup>2</sup>	80	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	30	mJ
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	42	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	nction Temperature Range -55 to 150	
Rejc	Thermal Resistance Junction-Case <sup>1</sup>	on-Case <sup>1</sup> 3.6	





N-Channel MOSFET



# IRFR3410TRPBF

N-Channel Enhancement Mode MOSFET

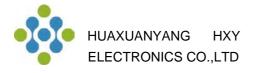
# Electrical Characteristics (TJ=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	teristic	I		1		
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250µA	100	-	-	V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	-	-	±100	nA
On Charac	teristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	1.0	1.5	2.2	V
<b>_</b>	Static Drain-Source on-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	-	37	48	mΩ
$R_{DS(on)}$	note3	V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A	-	39	55	mΩ
Dynamic C	Characteristics		-			
Ciss	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V,	-	1964	-	pF
Coss	Output Capacitance		-	90	-	pF
Crss	Reverse Transfer Capacitance	f=1.0MHz	-	74	-	pF
Qg	Total Gate Charge		-	20	-	nC
$Q_gs$	Gate-Source Charge	$V_{DS}$ =80V, $I_{D}$ =20A,	-	3.1	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge	V <sub>GS</sub> =4.5V	- 14		-	nC
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-on Delay Time		-	11	-	ns
tr	Turn-on Rise Time	V <sub>DS</sub> =80V, I <sub>D</sub> =20A,	-	91	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	R <sub>G</sub> =3.1Ω, V <sub>GS</sub> =4.5V	-	40	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	71	-	ns
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings				
ls	Maximum Continuous Drain to Source Diode Forward Current		-	-	27	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Dio	rce Diode Forward Current		-	80	Α
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =20A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 004	-	64	-	ns
Qrr	Body Diode Reverse Recovery Charge	l⊧=20A, dl/dt=100A/µs	-	152	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : T\_J=25  $^\circ \!\! C$  ,V\_DD=50V,V\_G=10V,L=0.5mH,Rg=25\Omega,I\_{AS}= 11A

3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



# IRFR3410TRPBF N-Channel Enhancement Mode MOSFET

**Typical Performance Characteristics** 

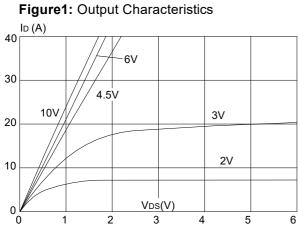
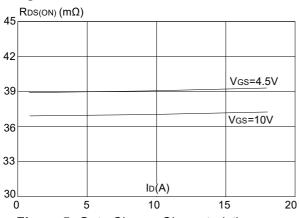
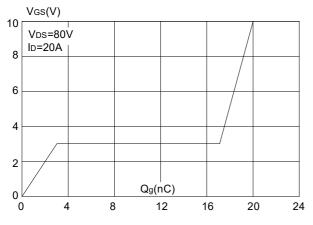
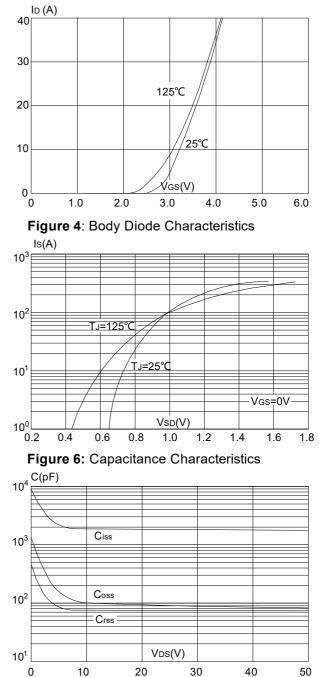


Figure 3: On-resistance vs. Drain Current









#### Figure 2: Typical Transfer Characteristics



**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature

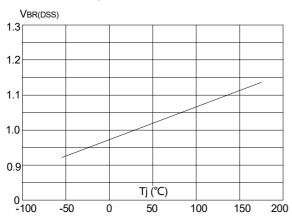


Figure 9: Maximum Safe Operating Area

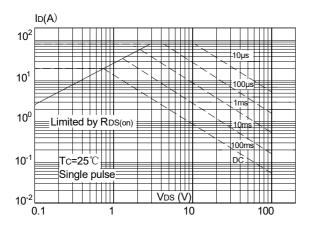
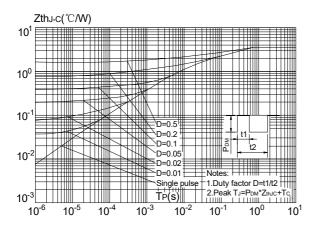


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



**Figure 8:** Normalized on Resistance vs. Junction Temperature

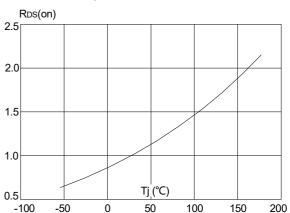
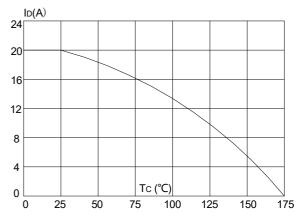
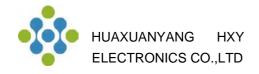
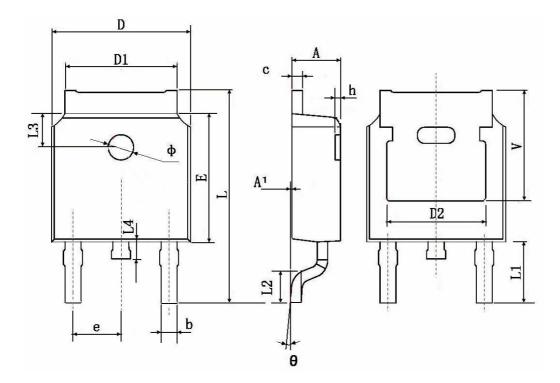


Figure 10: Maximum Continuous Drain Current vs. Case Temperature





# TO-252-2L Package Information



Ourseland	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483	TYP.	0.19	0 TYP.	
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900	TYP.	0.114 TYP.		
L2	1.400	1.700 0.055		0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0 °	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP. 0.211 TYP.			1 TYP.	



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